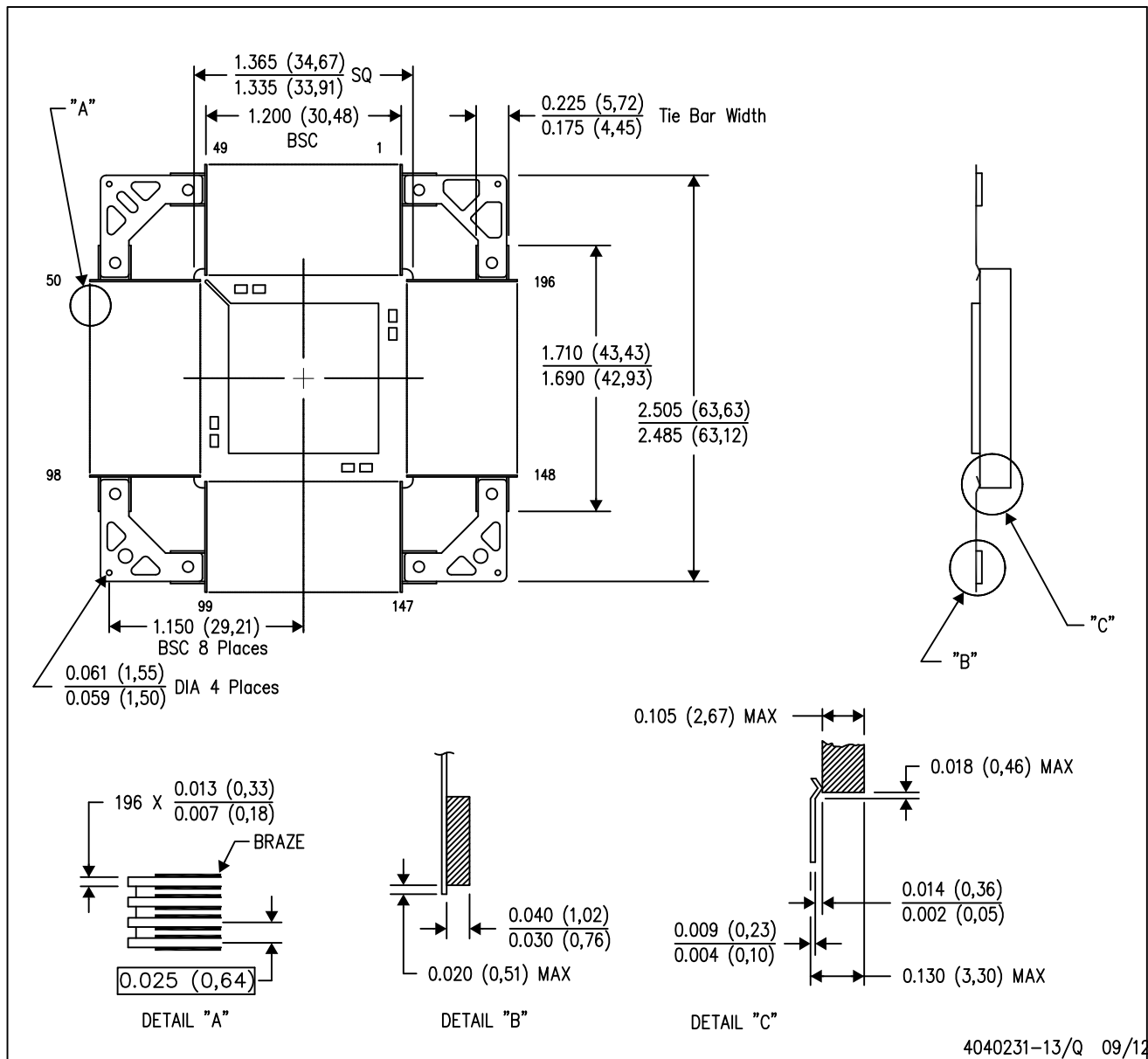


HFG (S-CQFP-F196)

CERAMIC QUAD FLATPACK WITH NCTB



4040231-13/Q 09/12

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